

5. (Allowed)

6. (Currently Amended) The An aqueous emulsion type photosolder resist composition according to claim 1, wherein obtained by neutralizing said resin (A) according to claim 1 is neutralized by with a base and made to be water-soluble.

7. (Currently Amended) The aqueous emulsion type photosolder resist composition according to claim 6, wherein said resin (A) has double bonds of 0.1×10^{-3} to 3.0×10^{-3} mol/g and the content of the carboxyl group of 30 to 200 mgKOH/g.

8. (Currently Amended) The aqueous emulsion type photosolder resist composition according to claim 6, wherein the ratio of the carboxyl group in said resin (A) and the cyclic ether group in said photocurable mixture (C) is (1.3/0.7) to (0.7/1.3) by mole ratio.

9. (Currently Amended) The aqueous emulsion type photosolder resist composition according to claims claim 6, further containing a coloring pigment.

10. (Currently Amended) The aqueous emulsion type photosolder resist composition according to claim 6, wherein the content of said inorganic filler (B) is 5 to 75 parts by weight in 100 parts by weight of solid content of the entire photosolder resist composition.

11. (Allowed)

12. (Withdrawn)